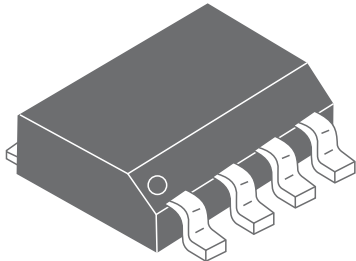
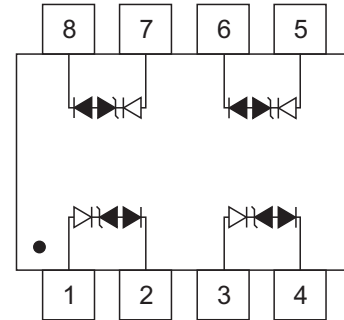


# Electro-Static Discharge TLSD2.8K4B Low Capacitance TVS Diode

## SOP-08



## Pin Configuration



## Features

- 400 Watts Peak Pulse Power per Line ( $t_p=8/20\mu s$ )
- Protects two line pairs (four lines)
- Low capacitance
- RoHS Compliant

## IEC Compatibility

- IEC61000-4-2 (ESD)  $\pm 15kV$  (air),  $\pm 8kV$  (contact)
- IEC61000-4-4 (EFT) 40A (5/50ns)
- IEC61000-4-5 (Lightning) 24A (8/20 $\mu s$ )

## Applications

- 10/100/1000 Ethernet
- WAN/LAN Equipment
- Test & Measurement Equipment
- Switching Systems
- Instrumentation
- Audio/Video Inputs

## Mechanical Characteristics

- JEDEC SOP-08 Package
- Molding Compound Flammability Rating:UL 94V-O
- Weight 70 Milligrams(Approximate)
- Quantity Per Reel:500pcs
- Reel Size:7 inch
- Lead Finish:Lead Free

Maximum Ratings( $T_A=25^{\circ}\text{C}$  unless otherwise specified )

Parameter	Symbol	Value	Units
Peak Pulse Power( $t_p=8/20\mu\text{s}$ )	$P_{PP}$	400	Watts
Lead Soldering Temperature	$T_L$	260(10 sec.)	$^{\circ}\text{C}$
Operating Temperature Range	$T_J$	-55~150	$^{\circ}\text{C}$
Storage Temperature Range	$T_{STG}$	-55~150	$^{\circ}\text{C}$

Electrical Characteristics( $T_A=25^{\circ}\text{C}$  unless otherwise specified )

TLSD2.8K4B(Marking:SLVU 2.8-4)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Reverse Stand-off Voltage	$V_{RWM}$				2.8	V
Breakdown Voltage	$V_{BR}$	$I_T=1\text{mA}$	3.0			V
Clamping Voltage	$V_C$	$I_{PP}=1\text{A}, t_p=8/20\mu\text{s}$			8.5	V
		$I_{PP}=10\text{A}, t_p=8/20\mu\text{s}$			15	V
Reverse Leakage Current	$I_R$	@ $V_{RWM}$			1	$\mu\text{A}$
Junction Capacitance	$C_{I/O}$	0Vdc, f=1MHz Between I/O Pins and GND		3		pF

Ratings and Characteristic Curves

Fig.1 Non-Repetitive Pulse Power vs.Pulse Time

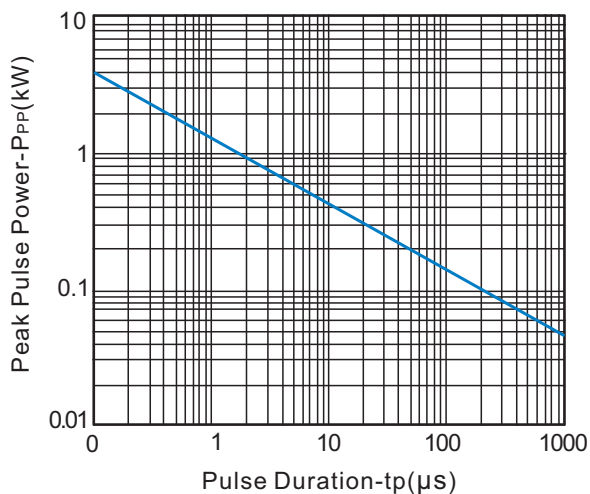
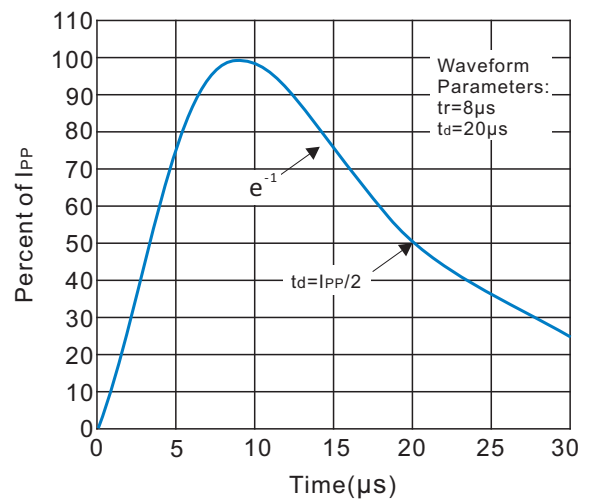
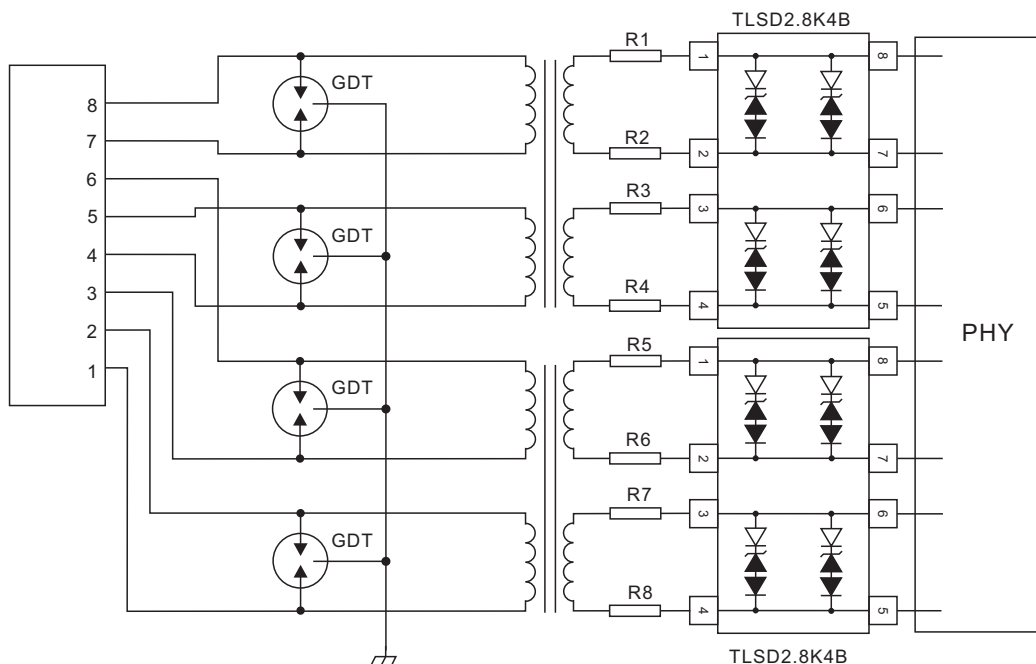


Fig.2 Pulse Waveform

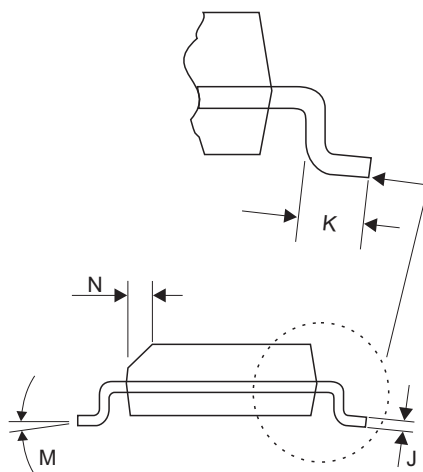
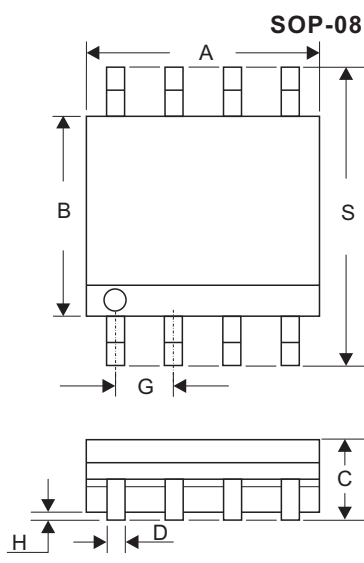


# Application

## RJ45 Protection

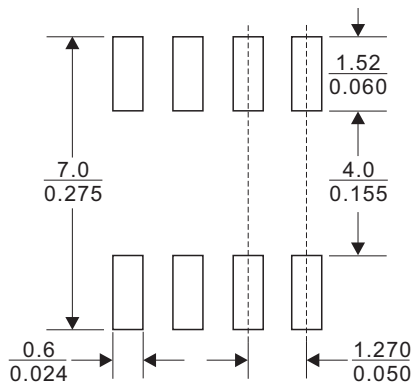


## Dimensions(SOP-08)



DIM	Millimeters		Inches	
	Min	Max	Min	Max
A	4.80	5.00	0.189	0.197
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
H	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0°	8°	0°	8°
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

### Recommended Mounting Pad Layout



Dimensions in ( millimeters / inches )

单击下面可查看定价，库存，交付和生命周期等信息

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